

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,094,676 B1
APPLICATION NO. : 10/719823
DATED : August 22, 2006
INVENTOR(S) : Chuen-Rong Leu et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On Title Page, Item (54) should read,
METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR.

Column 53

Lines 31-36, "providing a metal base . . . of the metal base;" is a subparagraph.
Line 33, delete ";" after "the".

Column 55

Lines 46-51, "providing a metal base . . . of the metal base;" is a subparagraph.
Line 48, delete ";" after "the".

Column 57

Lines 56-61, "providing a metal base . . . of the metal base;" is a subparagraph.
Line 58, delete ";" after "the".

Column 60

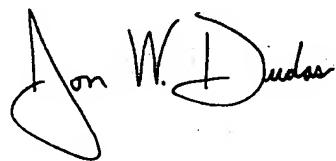
Lines 15-20, "providing a metal base . . . of the metal base;" is a subparagraph.
Line 17, delete ";" after "the".

Column 71

Line 16, change "291" to -- 293 --.

Signed and Sealed this

Twenty-fourth Day of October, 2006



JON W. DUDAS
Director of the United States Patent and Trademark Office